

SN54S260, SN74S260 DUAL 5-INPUT POSITIVE-NOR GATES

SDLS208

DECEMBER 1983 — REVISED MARCH 1988

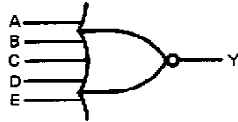
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

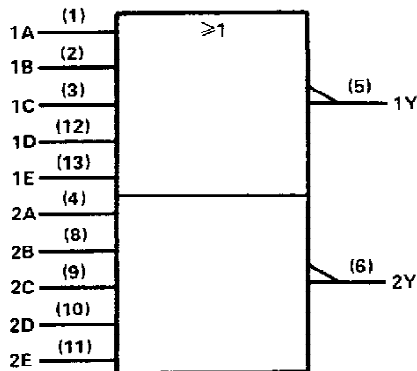
These devices contain two independent 5-input positive -NOR gates. They perform the Boolean function $Y = A + B + C + D + E$ in positive logic.

The SN54S260 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74S260 is characterized for operation from 0°C to 70°C .

logic diagram (each gate)



logic symbol†

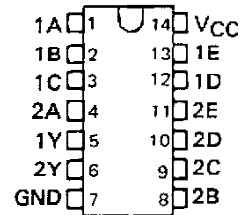


†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

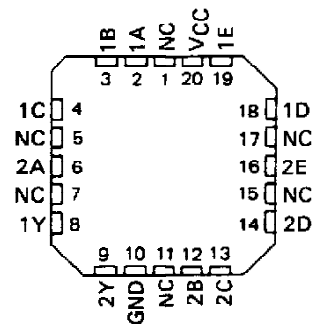
SN54S260 . . . J OR W PACKAGE
SN74S260 . . . D OR N PACKAGE

(TOP VIEW)



SN54S260 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

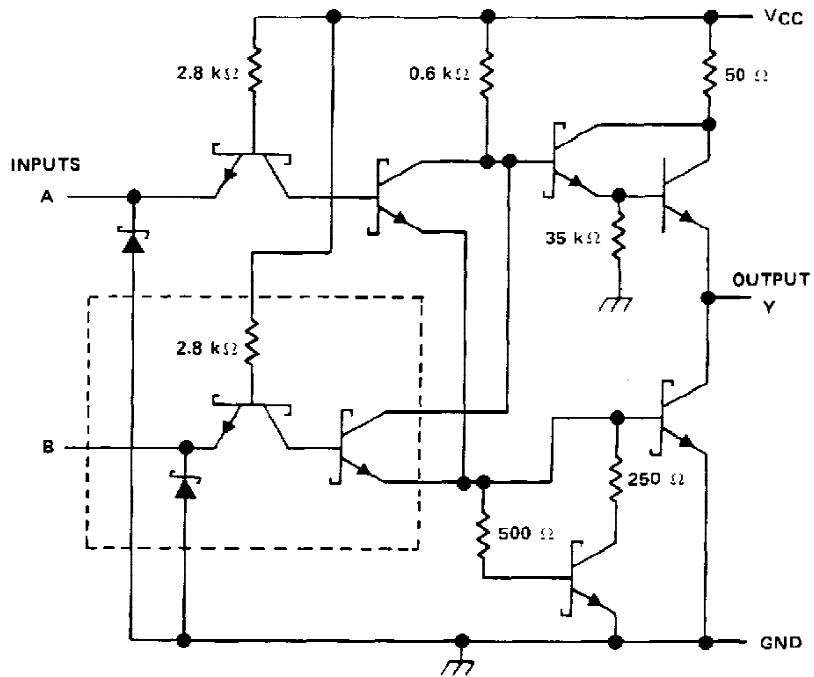
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SN54S260, SN74S260 DUAL 5-INPUT POSITIVE-NOR GATES

schematic (each gate)



Resistor values shown are nominal.
The portion of the schematic within the dashed-line is repeated for each additional input.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| | |
|---|--|
| Supply voltage, V_{CC} (see Note 1) | 7 V |
| Input voltage | 5.5 V |
| Operating free-air temperature range: SN54' | -55°C to 125°C |
| SN74' | 0°C to 70°C |
| Storage temperature range | -65°C to 150°C |

NOTE 1: Voltage values are with respect to network ground terminal.

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SN54S260, SN74S260 DUAL 5-INPUT POSITIVE-NOR GATES

recommended operating conditions

| | SN54S260 | | | SN74S260 | | | UNIT |
|---|----------|-----|-----|----------|-----|------|------|
| | MIN | TYP | MAX | MIN | TYP | MAX | |
| V _{CC} Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| V _{IH} High-level input voltage | 2 | | | 2 | | | V |
| V _{IL} Low-level input voltage | 0.8 | | | 0.8 | | | V |
| I _{OH} High-level output current | -1 | | | -1 | | | mA |
| I _{OL} Low-level output current | 20 | | | 20 | | | mA |
| T _A Operating free-air temperature | -55 | | | 125 | | | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS † | SN54S260 | | | SN74S260 | | | UNIT | |
|-------------------|---|----------|------|------|----------|------|------|------|----|
| | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | | |
| V _{IK} | V _{CC} = MIN, I _I = -18 mA | -1.2 | | | -1.2 | | | V | |
| V _{OH} | V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = -1 mA | 2.5 | 3.4 | | 2.7 | 3.4 | V | | |
| V _{OL} | V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 20 mA | 0.5 | | | 0.5 | | | V | |
| I _I | V _{CC} = MAX, V _I = 5.5 V | 1 | | | 1 | | | mA | |
| I _{IH} | V _{CC} = MAX, V _{IH} = 2.7 V | 50 | | | 50 | | | µA | |
| I _{IL} | V _{CC} = MAX, V _{IL} = 0.8 V | -2 | | | -2 | | | mA | |
| I _{OS} § | V _{CC} = MAX | -40 | | -100 | -40 | | -100 | mA | |
| I _{CCH} | V _{CC} = MAX, V _I = 0 V | 17 | | | 17 | | | 29 | mA |
| I _{CCL} | V _{CC} = MAX, See Note 2 | 26 | | | 26 | | | 45 | mA |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|--------------|-------------|--|-----|-----|-----|------|
| t _{PLH} | Any | Y | R _L = 280 Ω, C _L = 15 pF | | 4 | 5.5 | ns |
| t _{PHL} | | | | | 4 | 6 | ns |

NOTE 3: See General Information Section for load circuits and voltage waveforms.


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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN54S260J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN74S260D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S260DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S260DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S260DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S260DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S260DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S260N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S260N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74S260NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SNJ54S260FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54S260J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54S260W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

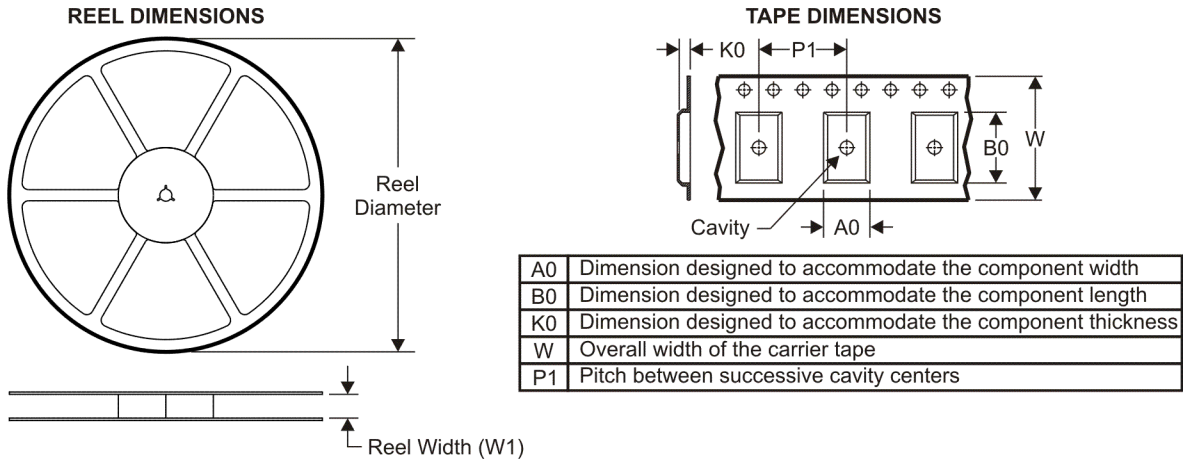
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74S260DR | SOIC | D | 14 | 2500 | 330.0 | 16.0 | 7.0 | 9.0 | 2.0 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74S260DR | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

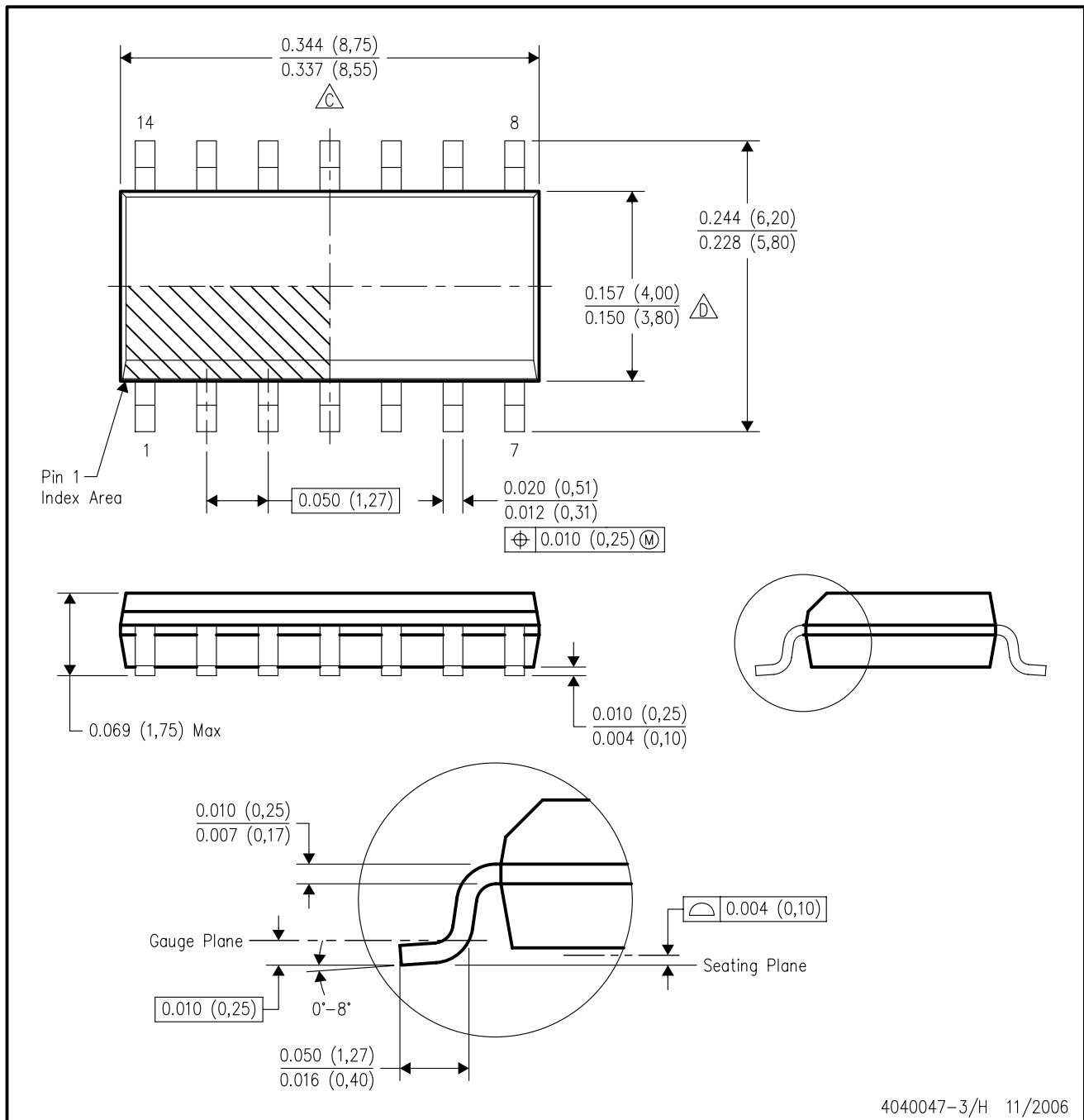


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.